

SN54ABT2952A, SN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCBS203D – AUGUST 1992 – REVISED JANUARY 1998

- State-of-the-Art **EPIC-IITM** BiCMOS Design Significantly Reduces Power Dissipation
- Two 8-Bit Back-to-Back Registers Store Data Flowing in Both Directions
- Noninverting Outputs
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model ($C = 200$ pF, $R = 0$)
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

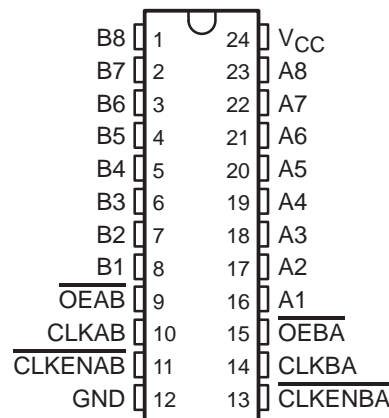
description

The 'ABT2952A transceivers consist of two 8-bit back-to-back registers that store data flowing in both directions between two bidirectional buses. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable (CLKENAB or CLKENBA) input is low. Taking the output-enable ($\overline{\text{OEAB}}$ or $\overline{\text{OEBA}}$) input low accesses the data on either port.

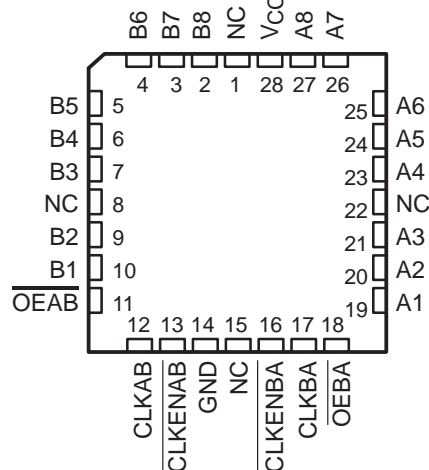
To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT2952A is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABT2952A is characterized for operation from -40°C to 85°C .

SN54ABT2952A . . . JT OR W PACKAGE
SN74ABT2952A . . . DB, DW, PW, OR NT PACKAGE
(TOP VIEW)



SN54ABT2952A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection



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**TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

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OCTAL BUS TRANSCEIVERS AND REGISTERS
WITH 3-STATE OUTPUTS

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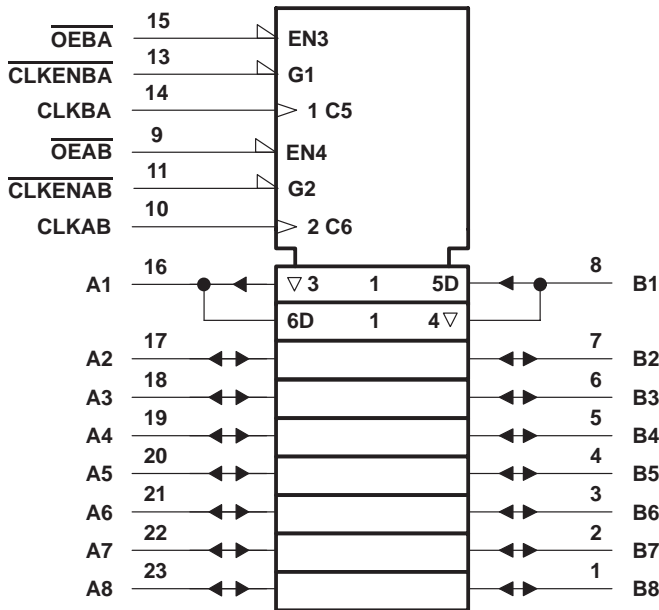
FUNCTION TABLE†

INPUTS				OUTPUT B
CLKENAB	CLKAB	OEAB	A	
H	X	L	X	B ₀ ‡
X	H or L	L	X	B ₀ ‡
L	↑	L	L	L
L	↑	L	H	H
X	X	H	X	Z

† A-to-B data flow is shown; B-to-A data flow is similar, but uses $\overline{\text{CLKENBA}}$, CLKBA , and $\overline{\text{OEBA}}$.

‡ Level of B before the indicated steady-state input conditions were established

logic symbol§

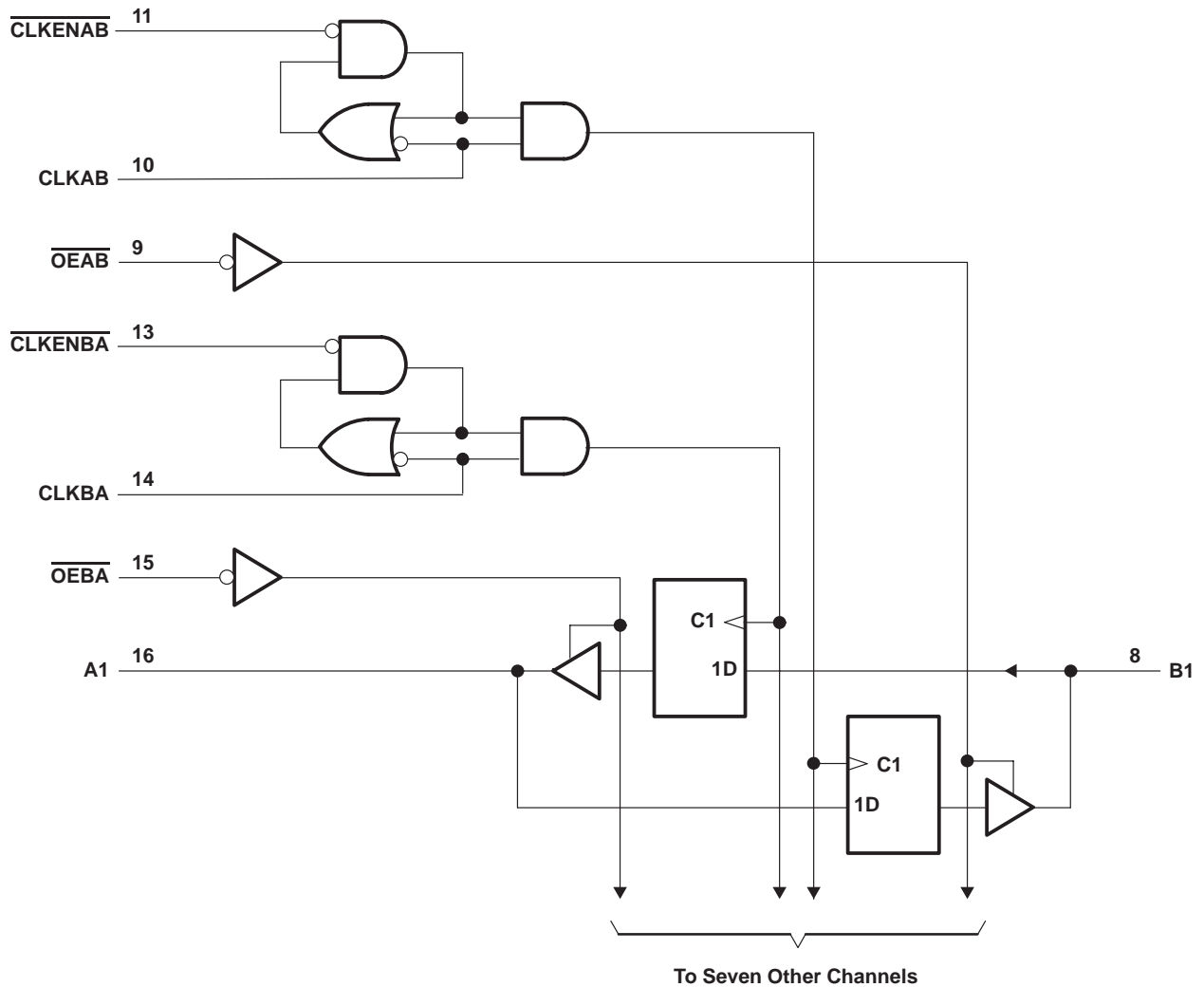


§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

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logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

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OCTAL BUS TRANSCEIVERS AND REGISTERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O : SN54ABT2952A	96 mA
SN74ABT2952A	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	104°C/W
DW package	81°C/W
NT package	67°C/W
PW package	120°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		SN54ABT2952A		SN74ABT2952A		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled			10	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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OCTAL BUS TRANSCEIVERS AND REGISTERS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T _A = 25°C			SN54ABT2952A		SN74ABT2952A		UNIT		
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX			
V _{IK}		V _{CC} = 4.5 V, I _I = -18 mA	-1.2			-1.2		-1.2		V		
V _{OH}		V _{CC} = 4.5 V, I _{OH} = -3 mA	2.5			2.5		2.5		V		
		V _{CC} = 5 V, I _{OH} = -3 mA	3			3		3				
		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2					
			I _{OH} = -32 mA	2*					2			
V _{OL}		V _{CC} = 4.5 V	I _{OL} = 48 mA	0.55			0.55		V			
			I _{OL} = 64 mA	0.55*			0.55					
V _{hys}			100							mV		
I _I	Control inputs	V _{CC} = 5.5 V, V _I = V _{CC} or GND	±1			±1		±1		μA		
	A or B ports		±100			±100		±100				
I _{OZH} ‡		V _{CC} = 5.5 V, V _O = 2.7 V	50*			10		50		μA		
I _{OZL} ‡		V _{CC} = 5.5 V, V _O = 0.5 V	-50*			-10		-50		μA		
I _{off}		V _{CC} = 0, V _I or V _O ≤ 4.5 V	±100*					±100		μA		
I _{CEX}		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50			50		μA	
I _O §		V _{CC} = 5.5 V, V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA		
I _{CC}	A or B ports	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND	Outputs high			1		250		250		μA
			Outputs low			24		35		35		mA
			Outputs disabled			0.5		250		250		250
ΔI _{CC} ¶		V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND	1.5			1.5		1.5		mA		
C _i	Control inputs	V _I = 2.5 V or 0.5 V	3.5							pF		
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V	7.5							pF		

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				V _{CC} = 5 V, T _A = 25°C		SN54ABT2952A		SN74ABT2952A		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency			0	150	0	150	0	150	MHz
t _w	Pulse duration, CLK high or low			3.3		3.3		3.3		ns
t _{su}	Setup time before CLK↑	A or B	High or low	2.5		3		2.5		ns
		CLKEN		3		3		3		
t _h	Hold time after CLK↑	A or B		1.5		1.5		1.5		ns
		CLKEN		2		2		2		



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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

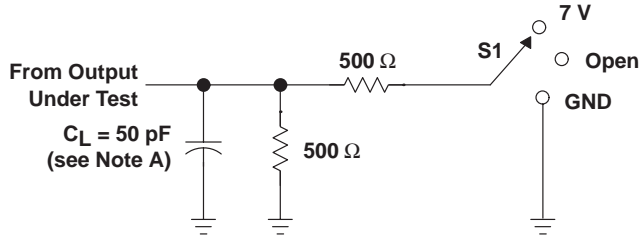
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$			SN54ABT2952A		SN74ABT2952A		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{\max}			150			150		150		MHz
t_{PLH}	CLKAB or CLKBA	B or A	2	3.3	5.2	2	6.3	2	5.9	ns
t_{PHL}			2.5	4	6.1	2.5	6.8	2.5	6.3	
t_{PZH}	\overline{OEBA} or \overline{OEAB}	A or B	1.5	3.2	4.7	1.5	5.7	1.5	5.6	ns
t_{PZL}			2	3.7	5.7	2	6.7	2	6.6	
t_{PHZ}	\overline{OEBA} or \overline{OEAB}	A or B	1.5	3.5	5.1	1.5	6.5	1.5	6.4	ns
t_{PLZ}			1.5	3.4	5.9	1.5	6.7	1.5	6.2	



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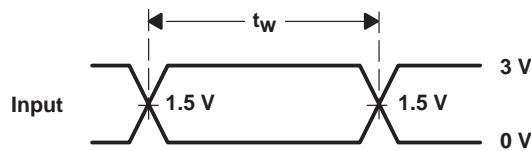
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PARAMETER MEASUREMENT INFORMATION

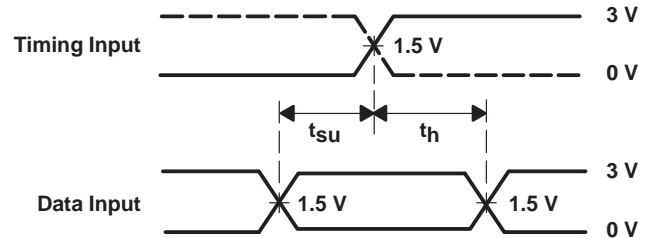


LOAD CIRCUIT

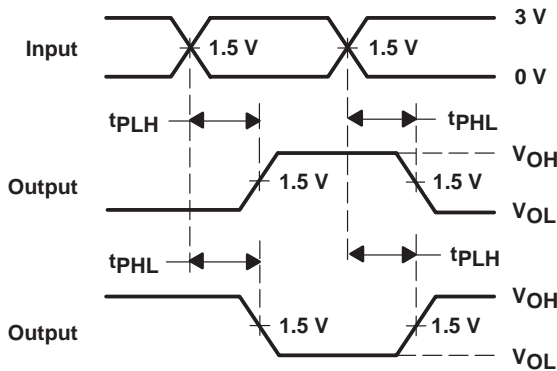
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



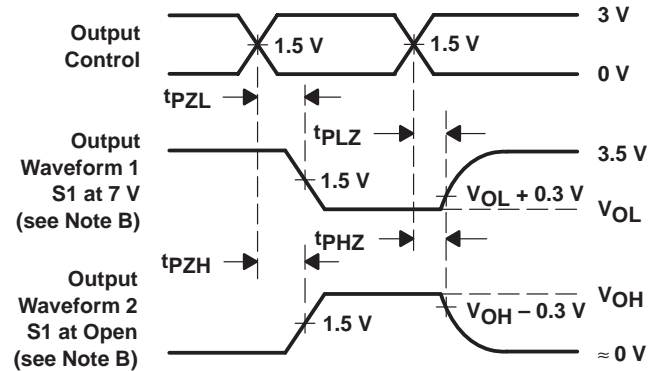
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9308602Q3A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9308602QKA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type
5962-9308602QLA	ACTIVE	CDIP	JT	24	1	TBD	A42 SNPB	N / A for Pkg Type
SN74ABT2952ADBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI
SN74ABT2952ADBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADBRE4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADBRG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ADWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ANSR	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ANSRE4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ANSRG4	ACTIVE	SO	NS	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT2952ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ABT2952ANTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54ABT2952AFK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ABT2952AJT	ACTIVE	CDIP	JT	24	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54ABT2952AW	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and

package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT2952ADBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74ABT2952ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ABT2952ANSR	SO	NS	24	2000	330.0	24.4	8.2	15.4	2.5	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT2952ADBR	SSOP	DB	24	2000	346.0	346.0	33.0
SN74ABT2952ADWR	SOIC	DW	24	2000	346.0	346.0	41.0
SN74ABT2952ANSR	SO	NS	24	2000	346.0	346.0	41.0

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

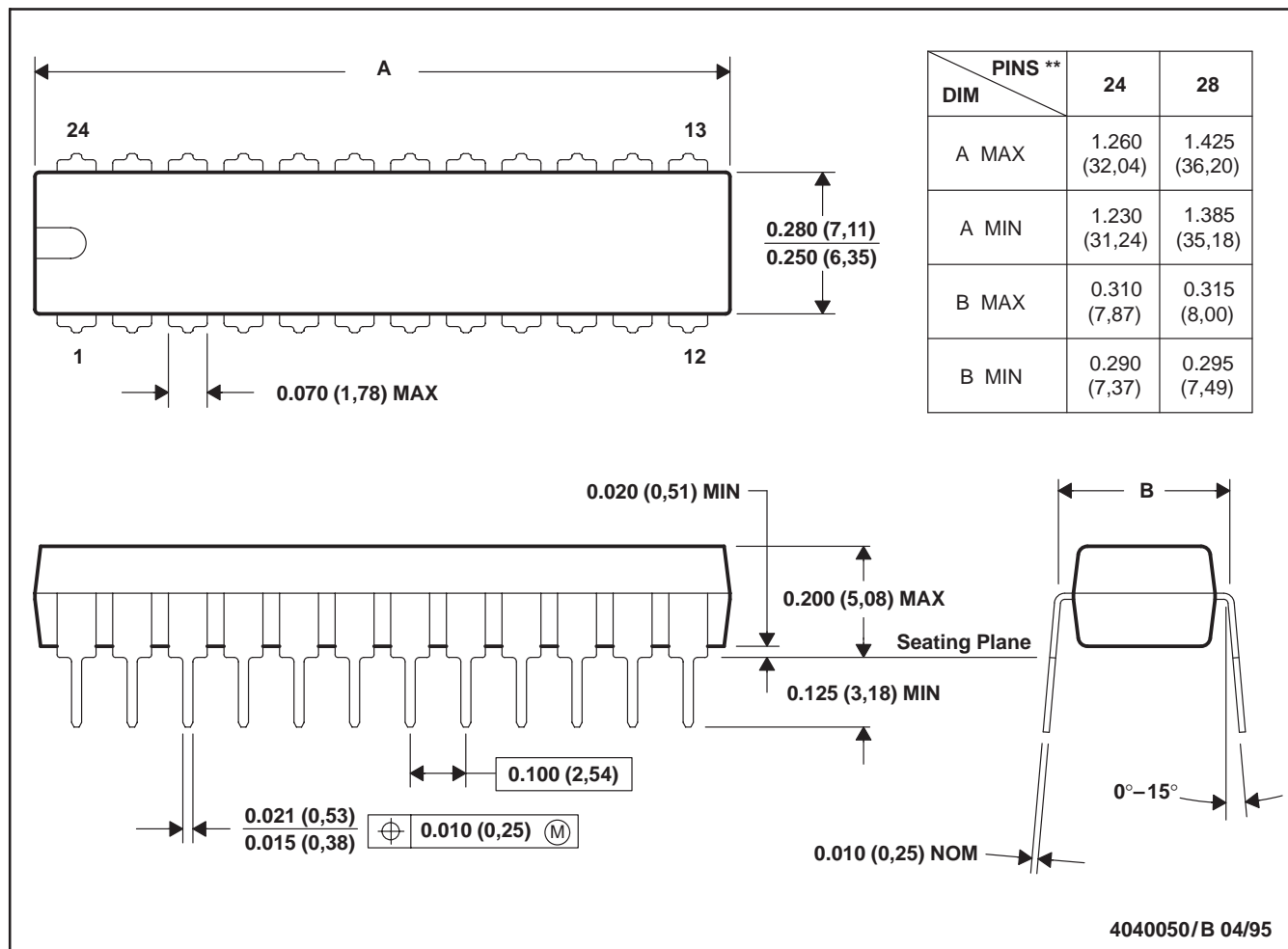


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

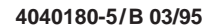
DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-013 variation AD.

CERAMIC DUAL FLATPACK

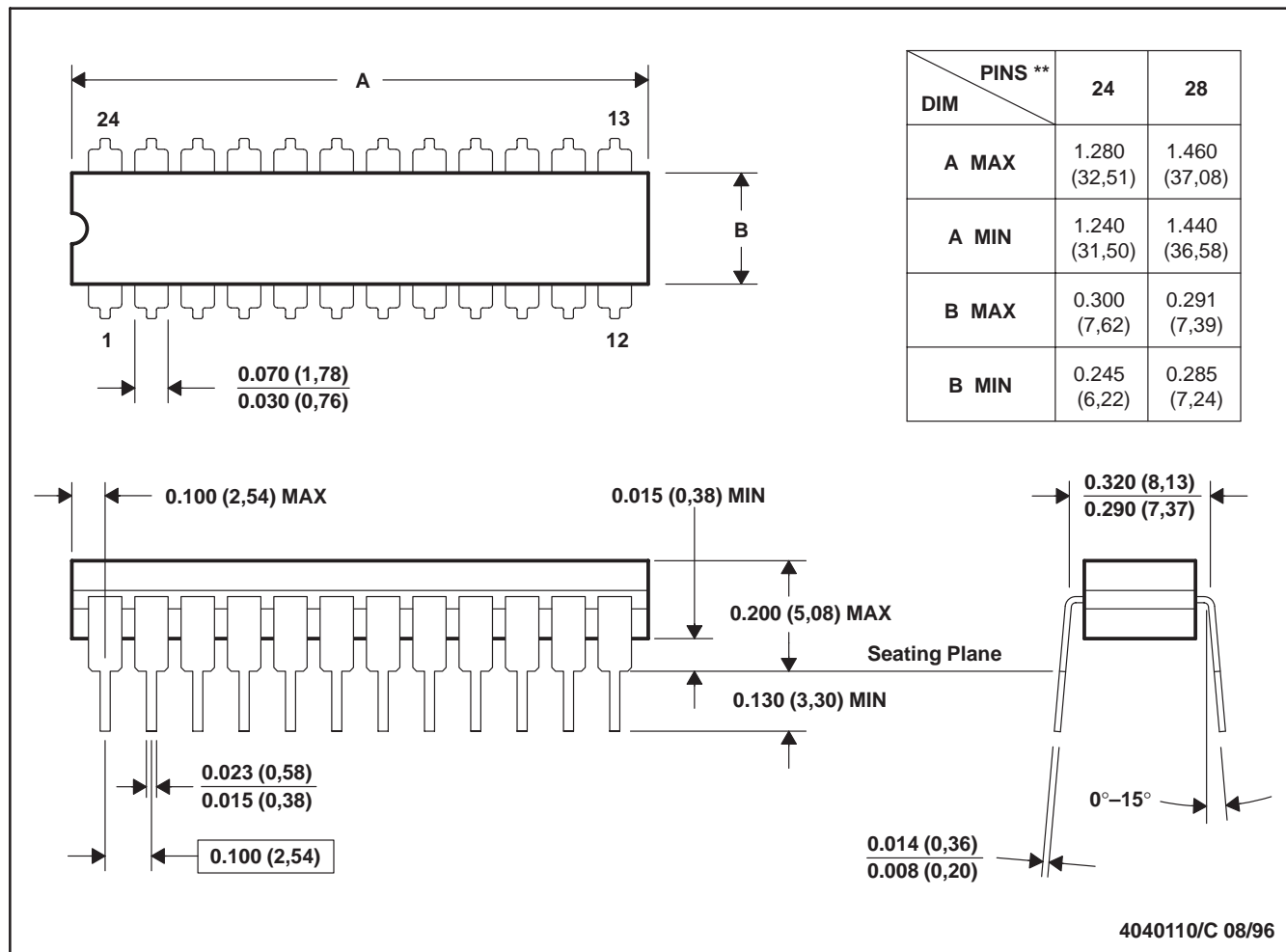


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JT (R-GDIP-T**)

CERAMIC DUAL-IN-LINE

24 LEADS SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification.
 - Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

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